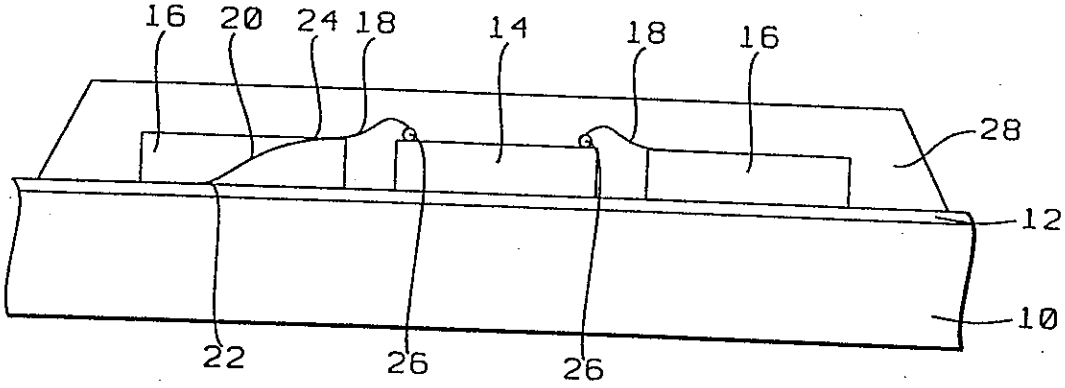


FIG. 1 – Prior Art

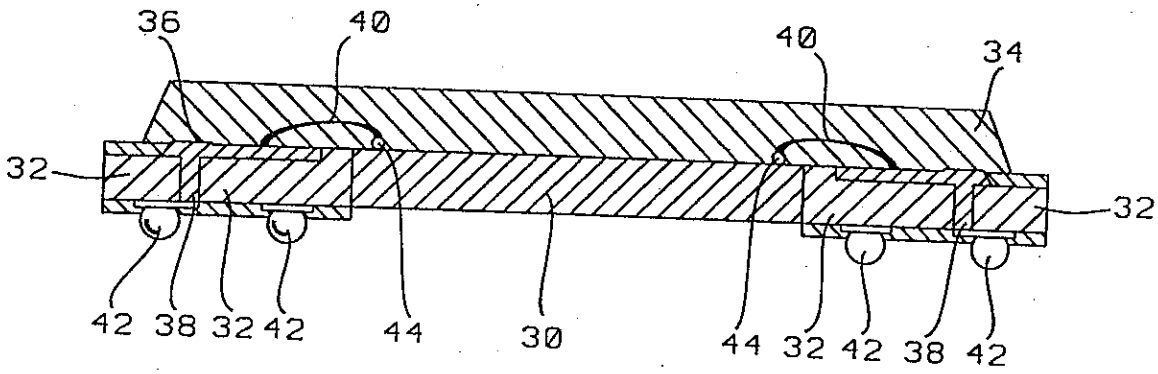


FIG. 2 – Prior Art

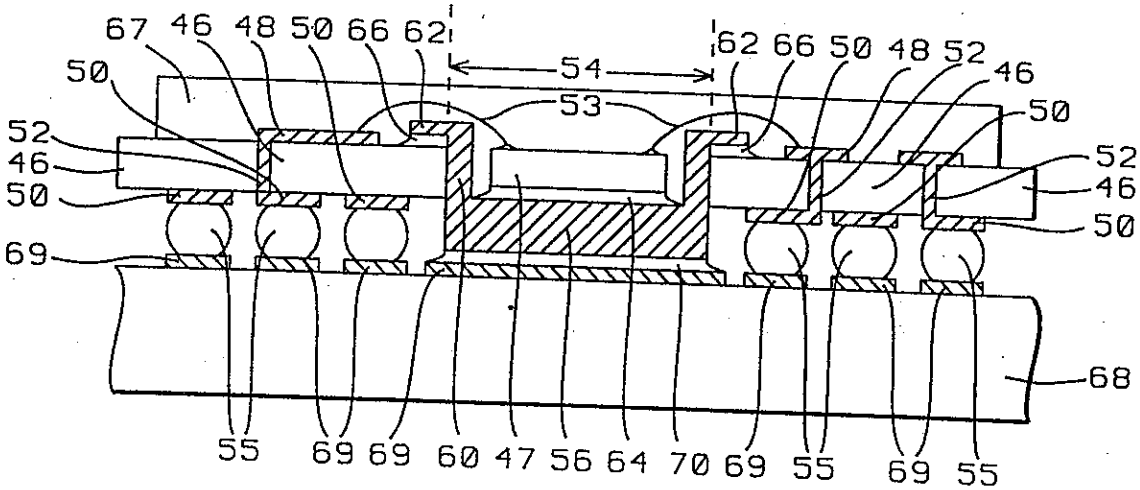


FIG. 3 – Prior Art

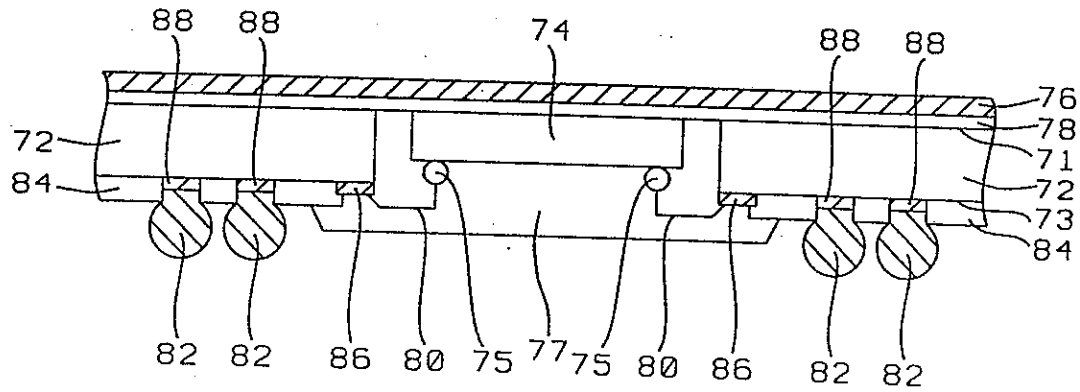


FIG. 4

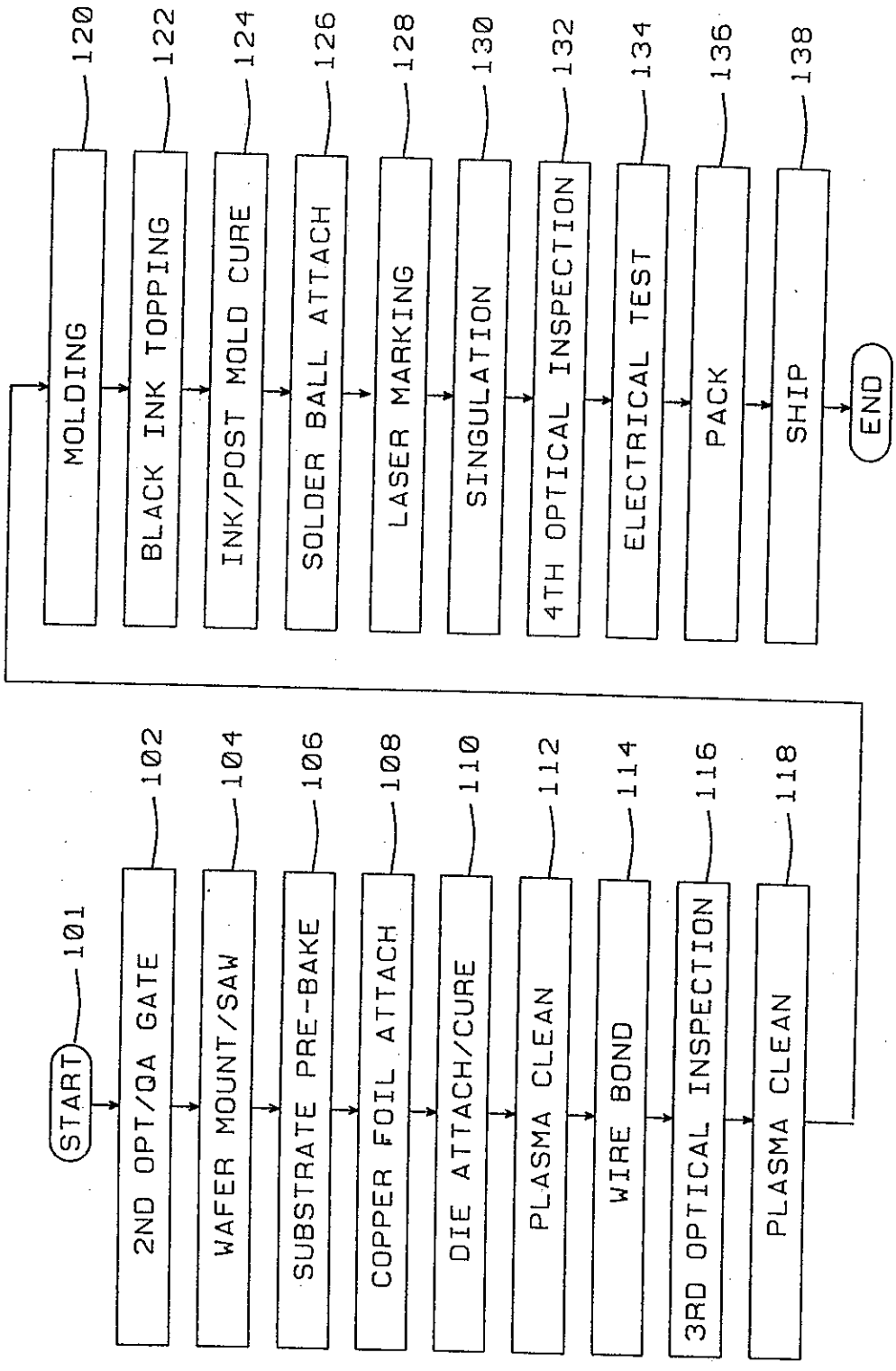

START
101
2ND OPT/QA GATE
102
WAFER MOUNT/SAW
104
SUBSTRATE PRE-BAKE
106
COPPER FOIL ATTACH
108
DIE ATTACH/CURE
110
PLASMA CLEAN
112
WIRE BOND
114
3RD OPTICAL INSPECTION
116
PLASMA CLEAN
118
MOLDING
120
BLACK INK TOPPING
122
INK/POST MOLD CURE
124
SOLDER BALL ATTACH
126
LASER MARKING
128
SINGULATION
130
4TH OPTICAL INSPECTION
132
ELECTRICAL TEST
134
PACK
136
SHIP
138
END

FIG. 5

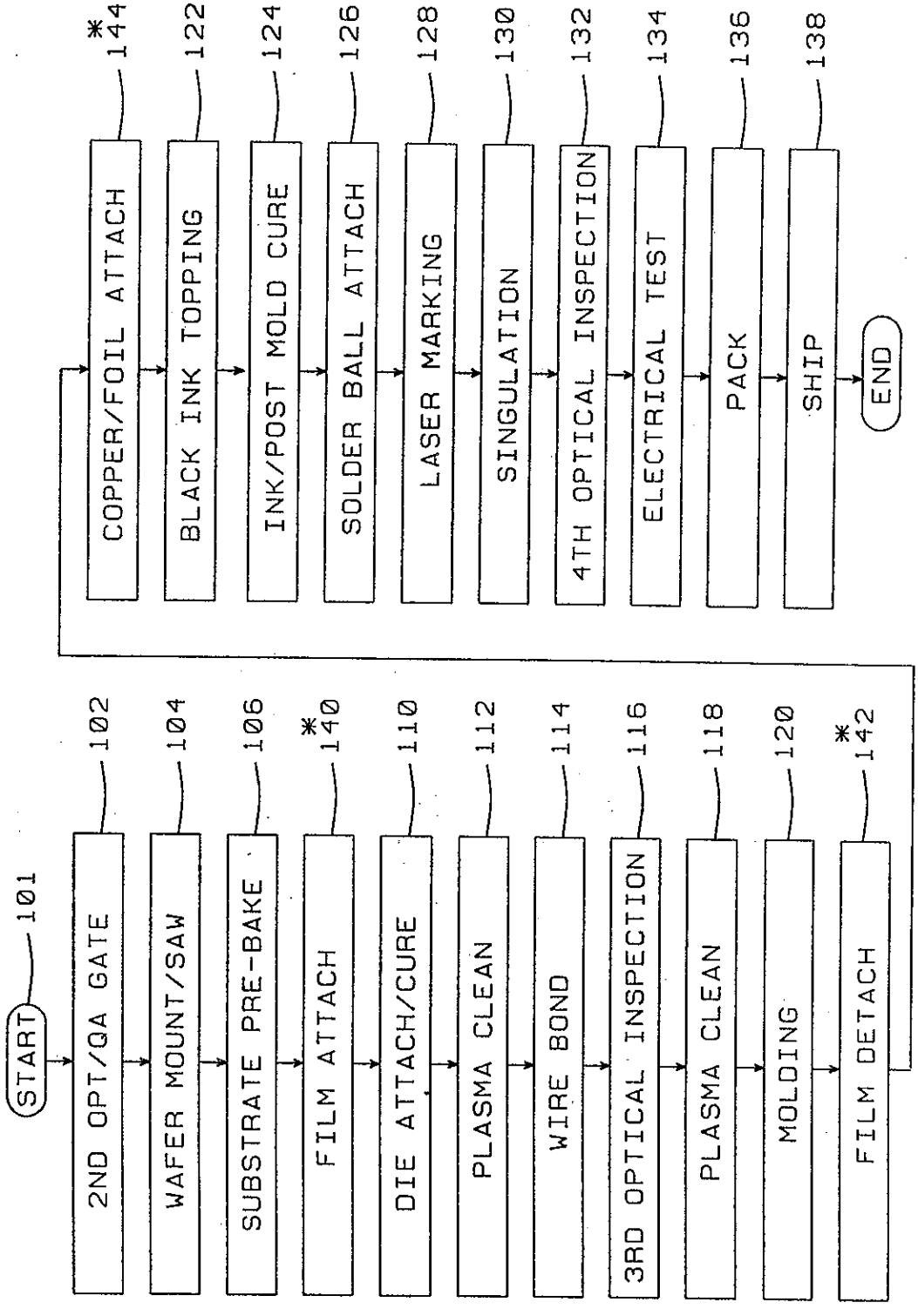

START
101
2ND OPT/QA GATE
102
WAFER MOUNT/SAW
104
SUBSTRATE PRE-BAKE
106
FILM ATTACH
*140
DIE ATTACH/CURE
110
PLASMA CLEAN
112
WIRE BOND
114
3RD OPTICAL INSPECTION
116
PLASMA CLEAN
118
MOLDING
120
FILM DETACH
*142
COPPER/FOIL ATTACH
*144
BLACK INK TOPPING
122
INK/POST MOLD CURE
124
SOLDER BALL ATTACH
126
LASER MARKING
128
SINGULATION
130
4TH OPTICAL INSPECTION
132
ELECTRICAL TEST
134
PACK
136
SHIP
138
END

FIG. 6